



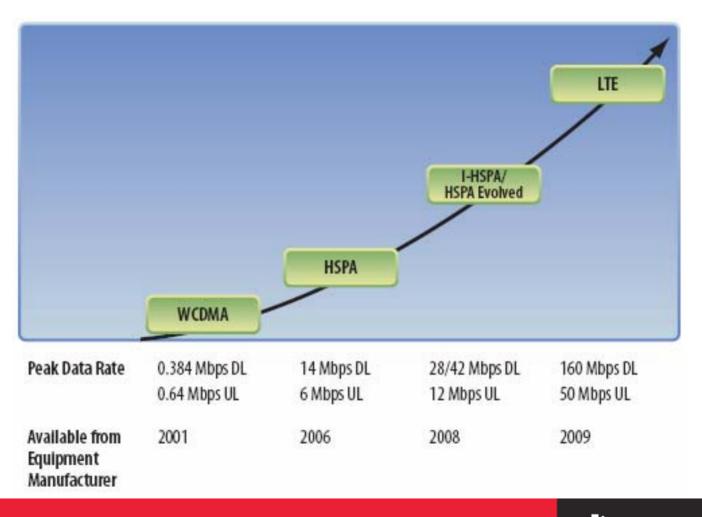
# The Mobile Broadband Evolution

### **COTS DSP Software for Wireless** Infrastructure TEMs

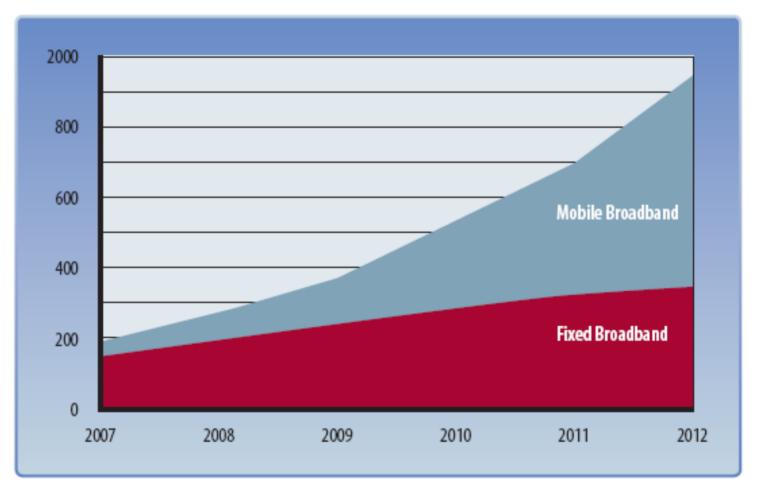
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# **Exponential Data Traffic Growth**



#### Forcasted Broadband Subscribers - Millions





#### Handling Increased Complexity While Lowering Cost

- Pressure from service providers, the carriers, is being exerted on TEMs to build the network elements that will power this major evolution in communications.
- Demand for systems that are
  - High performance
  - Highly available
  - Manageable
- Reduce capital and operating expenditures (CAPEX/OPEX)



#### Cost Efficient Data Plane Processing

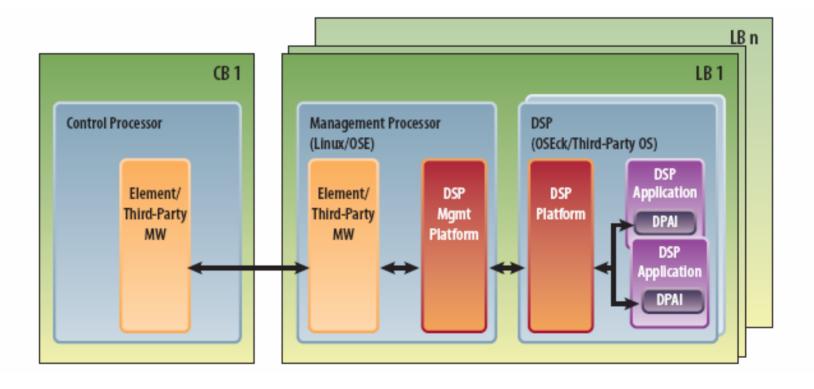
- Movement towards more standardized hardware and base software components for control plane
  - SCOPE Alliance
  - PICMG's AdvancedTCA™
- In the data plane the story is different
  - DSPs have used RTOSes and IPC mechanisms for over 10 years
  - On top of the OS, TEMs engage professional services projects to build essentially the same core management services over and over again.
- This "one-off" approach is simply no longer efficient from either a business or maintenance point of view

#### A Standard DSP SW Platform Product

- The industry demands a COTS approach
  - A pre-integrated DSP software platform targeting line cards found in applications like:
    - Base stations 3G deployments (e.g. WCDMA, TD-SCDMA), 802.16d/e WiMAX, High-Speed Packet Access (HSPA), and Long-Term Evolution (LTE)
    - Carrier infrastructure Media gateways and transcoding functions in 3G wireless networks
- Purpose
  - Reduce time to market
  - Lower costs
    - Development
    - I&V
    - Maintenance cost.
- The DSP software platform must provide
  - Highly efficient debug support
  - The basic management services needed to connect the data plane with the control plane
  - Graceful error handling for high availability

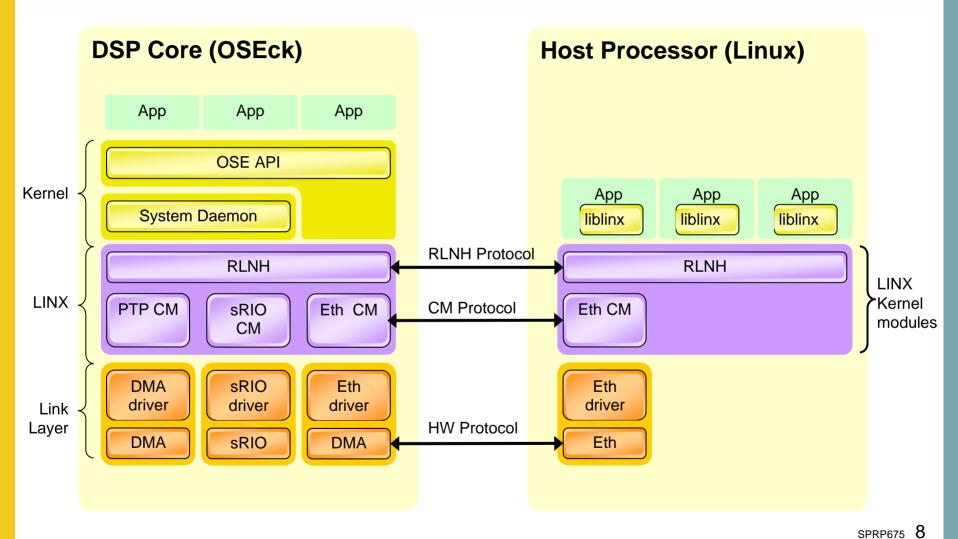


## Platform Overview



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#### IPC Communication: LINX

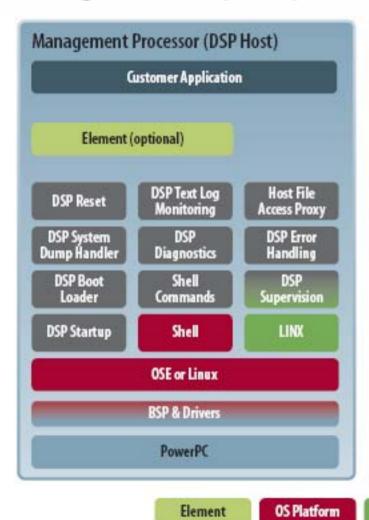


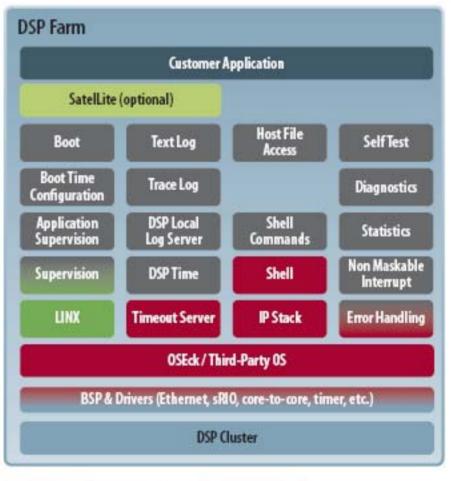


### **DSP Platform Services**

- Bootloading and Configuration
- Error Detection and Reporting
- Run-Time Debugging
- Post-Mortem Debugging

# **DSP Platform Services**





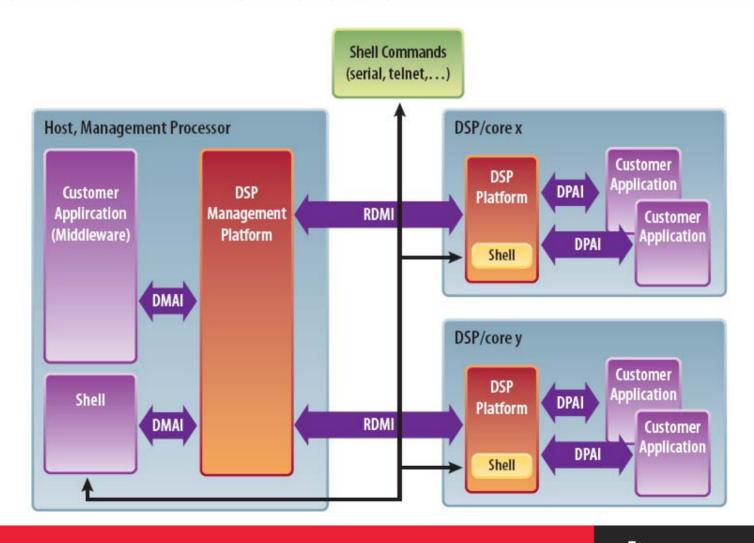
Processor

SPRP675 10

DSP Platform

LINX

### Platform Interfaces



## Element DSP Middleware

#### Element SatelLite

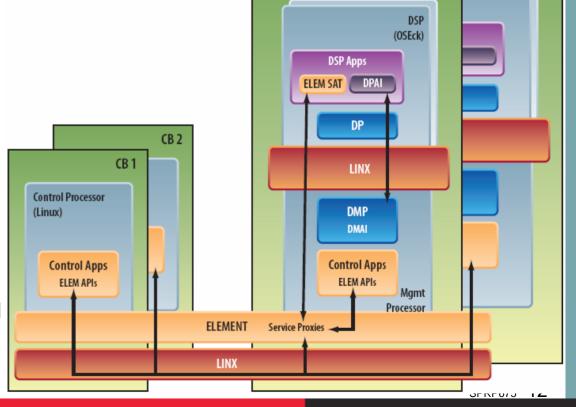
Extend Element Services into Devices (DSPs, NPUs, etc.)

 Extend Element Programming Model as Control Plane in DSP

#### Element Device Mgmt

- Control Embedded
   Device from Element

  Infrastructure
  - Reset, NMI, etc.
- Gather Status/Statistics from Device
  - Crash Dumps, Statistics, Trace Logs, etc.
- Manage Device Lifecycle
  - Image Load, Operational Monitoring, Debugging, Crash Detection and Recovery



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